电性参数

ǟ ˆ Ta=25Ņ˜ Absolute Maximum Rating(ta=25 Ņ)

ǟ Parameter	ˆ Symbol	ỵ Value	ɿ β Unit
w ˆ Max Power Dissipation˜	PD	75	mW
h ˆ Max Continuous Forward Current˜	IF	80	mA
ll ỵ ˆ Peak Forward Current˜	IFP	20	mA
ỉ h ɿˆ Max Reve n			

Optical-electrical paran

焊接指导（2）

Guideline for Soldering (2)

2. 清洗:

Cleaning

ضي U ą ˘ ضي ѣ ɢ 30Ņ ð Ӣ 3 № ˘ ѣ ɢ 50Ņ ð Ӣ 30 Â

ą ï ɾ ³ ╕ ╟˘ ѿ ą ╕ ѣ ψ LED غ № ᴴ Â

З ˘ ѿ ѡ ѣ 300W˘ Ɂ ↕ ˝ LED ᴴ Â

ï ʳ ’ ѿ ð Ɂ ψ LED ᴴ Â

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30Ņ for 3 minutes or 50 or 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also effective when for cleaning. But the influence of Ultrasonic cleaning on LEDs has fact such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pretest should be done to confirm whether any damage to LEDs will occur.

* **注意:** ѿ ʎ ↕ ѣ ɢ PCB غ Â ï ʳ ï ʃ غ ʒ˘ PCB غ Â

* **Note:** This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The technics in practise is inf